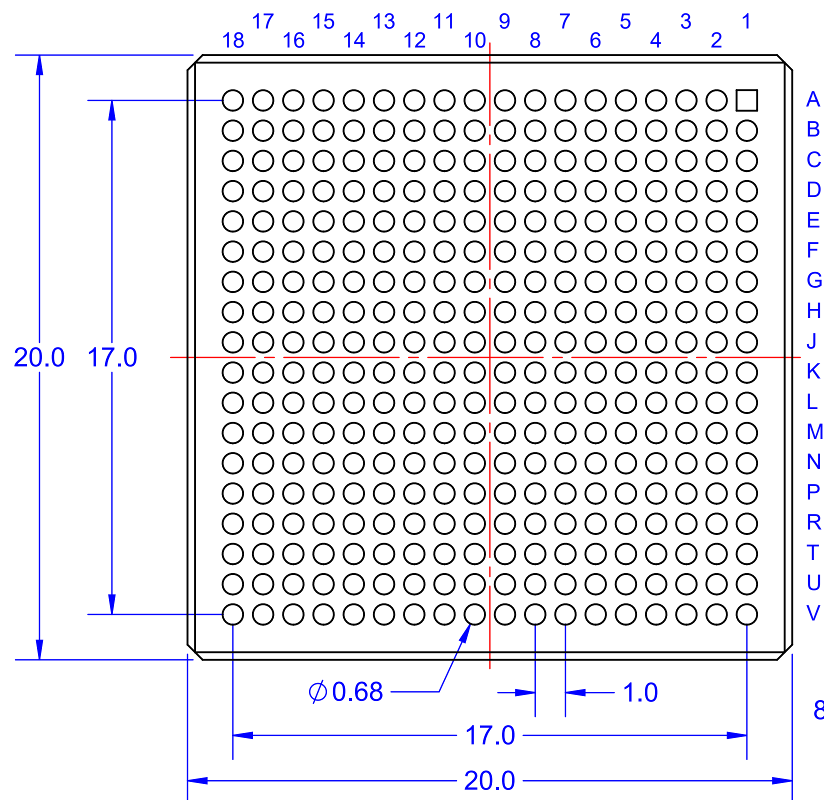
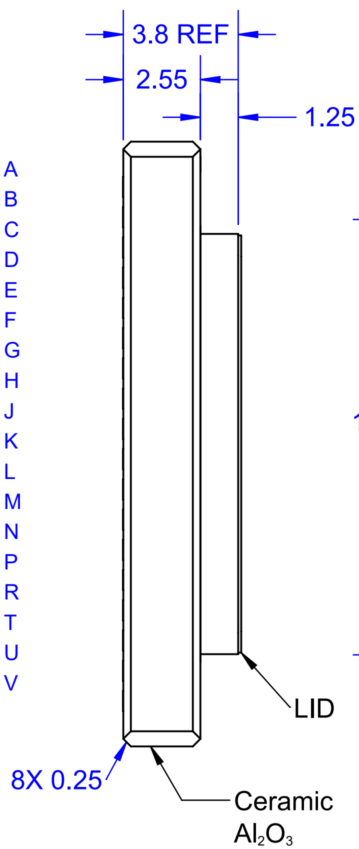
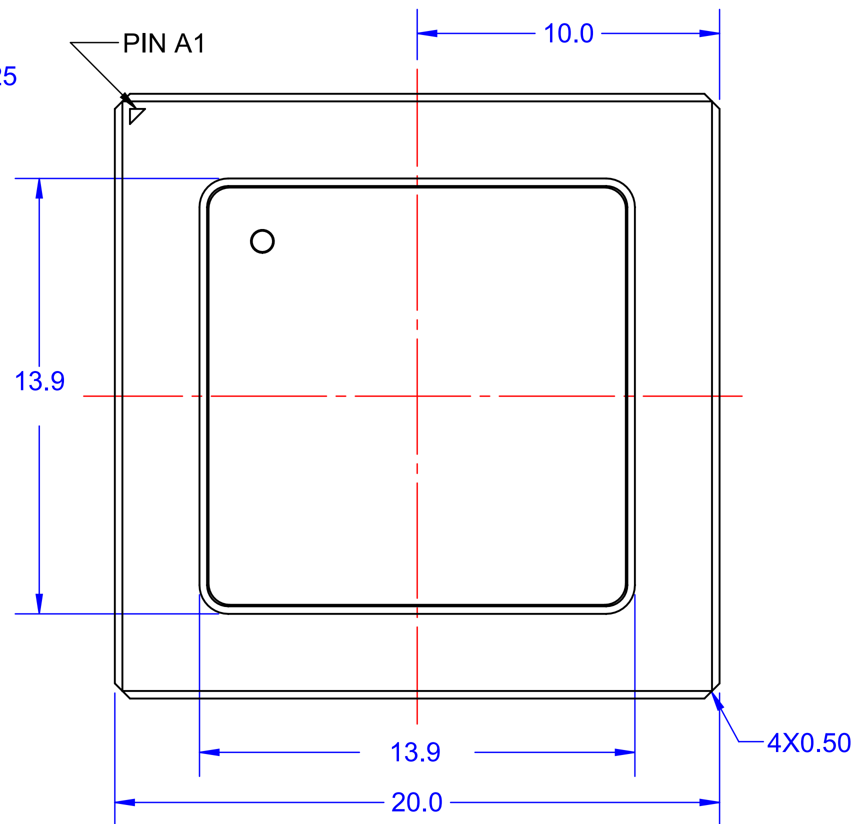






Notes: (Unless Otherwise Specified).
1) DIMENSIONS: MM.
2) SHOWN WITHOUT COLUMNS.
3) SHOWN WITH LID COVER ATTACHED.

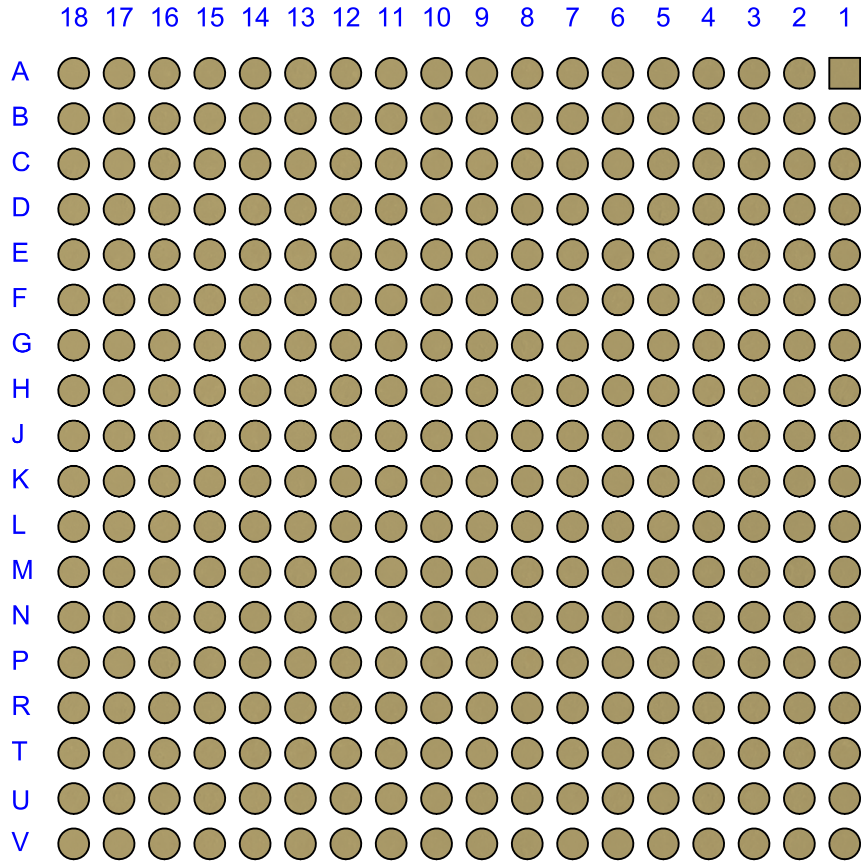
METALLIZATION:
Ni 1.27 ~ 8.89µm (50 ~ 350 micro-inch)
Au 0.50µm (38 micro-inch)

PART NUMBER OPTIONS			
PART NUMBER	DIE	SOLDER PIN	LID
CLGA323T1.0-18x18-D	YES	NONE	YES

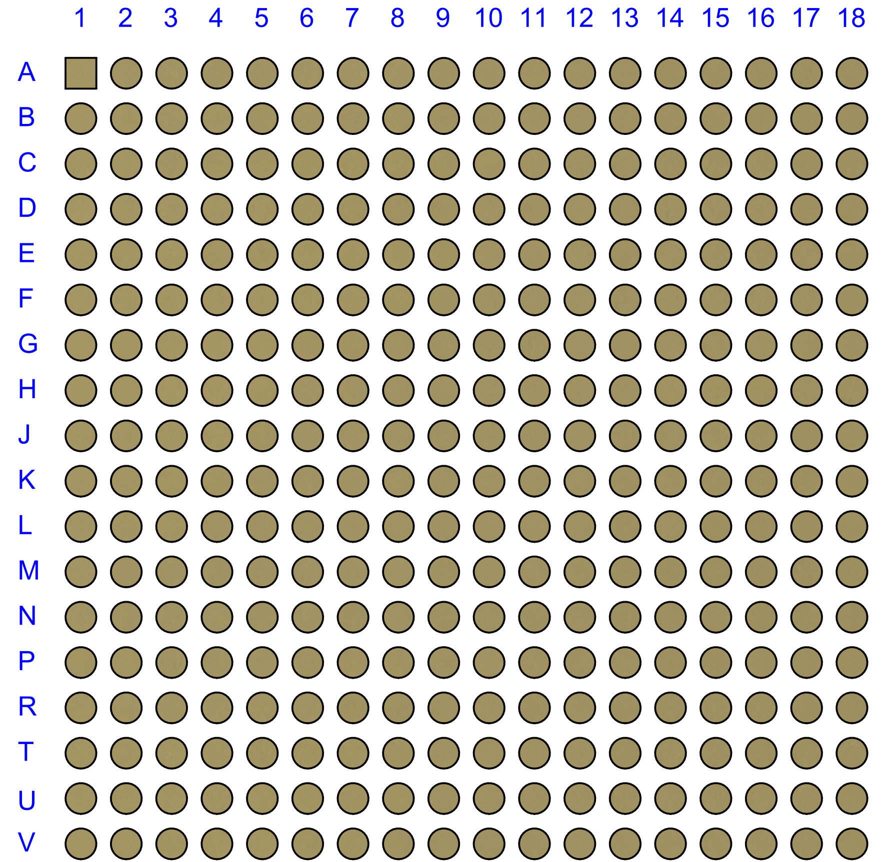
TITLE	CLGA323T1.0-18x18 CERAMIC LAND GRID ARRAY		
SCALE 4:1	SIZE A	DRAWING NO. 160172	REV A
DO NOT SCALE DRAWING		SHEET 1 OF 3	

PAD PATTERN

COLUMN (PAD) VIEW

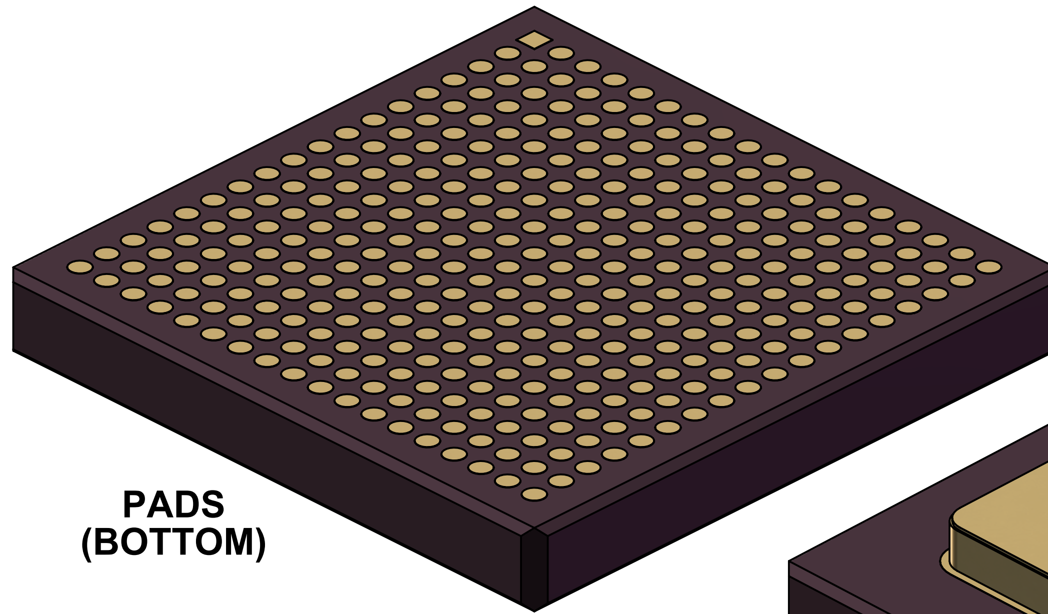


BOTTOM X-RAY VIEWED FROM TOP

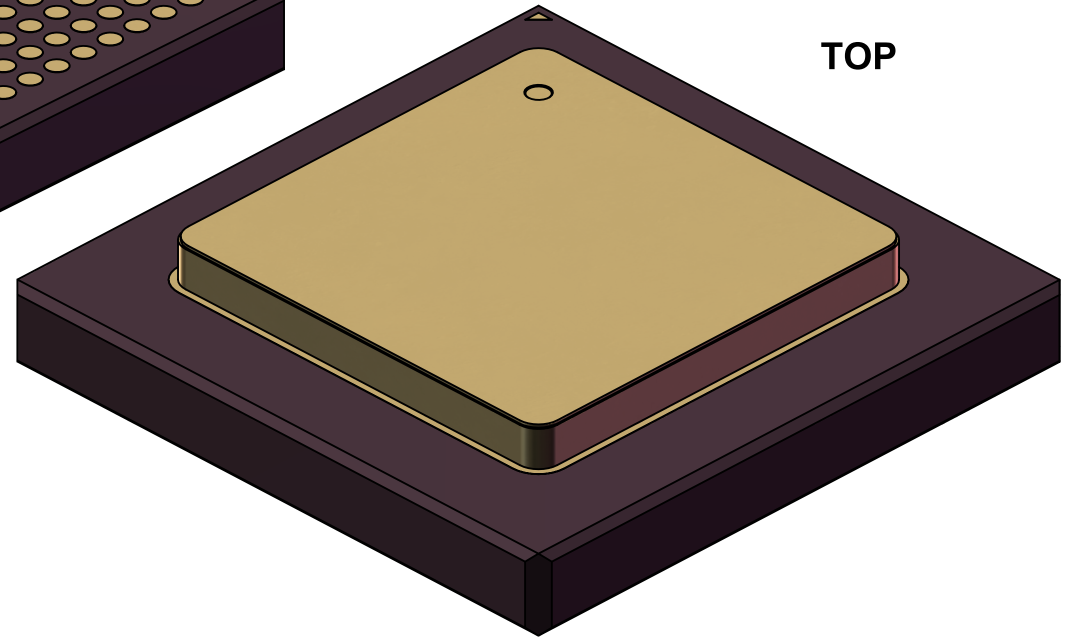


TopLine®			
TITLE CLGA323T1.0-18x18 CERAMIC LAND GRID ARRAY			
SCALE 2.5:1	SIZE A	DRAWING NO. 160172	REV A
DO NOT SCALE DRAWING		SHEET 2 OF 3	

MODEL
CLGA323T1.0-18x18-D
LID ATTACHED



PADS
(BOTTOM)



TOP

TopLine®

TITLE	CLGA323T1.0-18x18 CERAMIC LAND GRID ARRAY		
SCALE 5:1	SIZE A	DRAWING NO. 160172	REV A
DO NOT SCALE DRAWING		SHEET 3 OF 3	